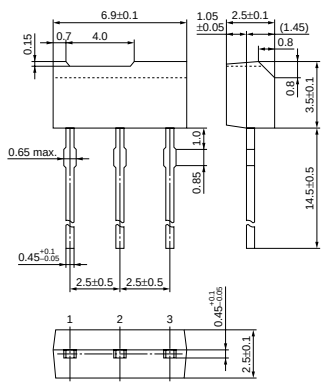
2SD2260

Silicon NPN triple diffusion planer type

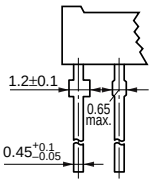
For high breakdown voltage general amplification

Unit: mm



Note: In addition to the lead type shown in the upper figure, the type as shown in the lower figure is also available.

1:Emitter
2:Collector
3:Base
MT1 Type Package



(HW type)

Features

- High collector breakdown voltage.
- Low collector to emitter saturation voltage $V_{CE(sat)}$.
- Allowing supply with the radial taping.

Absolute Maximum Ratings (Ta=25˚C)

Parameter	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	400	V
Collector to emitter voltage	V_{CEO}	400	V
Emitter to base voltage	V_{EBO}	5	V
Peak collector current	I_{CP}	100	mA
Collector current	I_C	70	mA
Collector power dissipation	P_C	600	mW
Junction temperature	T_j	150	˚C
Storage temperature	T_{stg}	–55 ~ +150	˚C

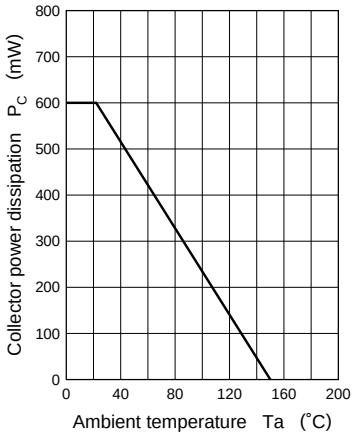
Electrical Characteristics (Ta=25˚C)

Parameter	Symbol	Conditions	min	typ	max	Unit
Collector cutoff current	I_{CBO}	V_{CB} = 100V, I_E = 0			2	µA
	I_{CEO}	V_{CE} = 100V, I_B = 0			2	µA
Collector to emitter voltage	V_{CEO}	I_C = 100µA, I_B = 0	400			V
Emitter to base voltage	V_{EBO}	I_E = 10µA, I_C = 0	5			V
Forward current transfer ratio	h_{FE}*	V_{CE} = 10V, I_C = 5mA	60		220	
Collector to emitter saturation voltage	$V_{CE(sat)}$	I_C = 50mA, I_B = 5mA		0.4	1.2	V
Transition frequency	f_T	V_{CB} = 10V, I_E = –10mA, f = 200MHz	50	80		MHz
Collector output capacitance	C_{ob}	V_{CB} = 10V, I_E = 0, f = 1MHz		4	10	pF

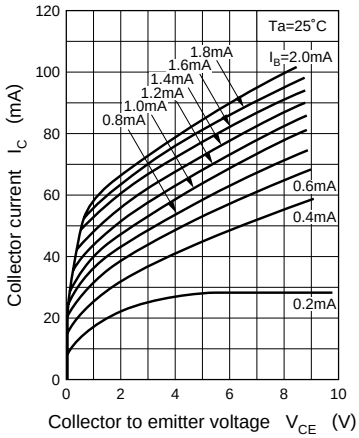
*h_{FE} Rank classification

Rank	Q	R
h_{FE}	60 ~ 150	100 ~ 220

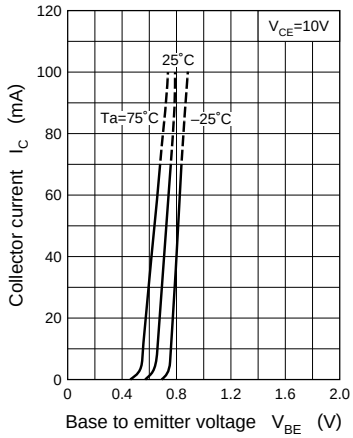
P_C — Ta



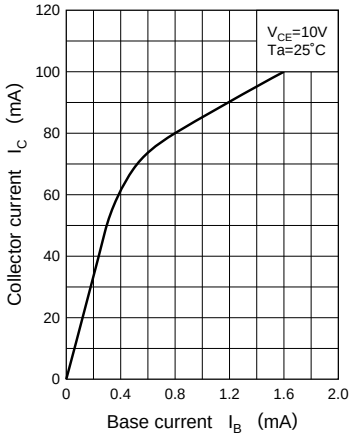
I_C — V_{CE}



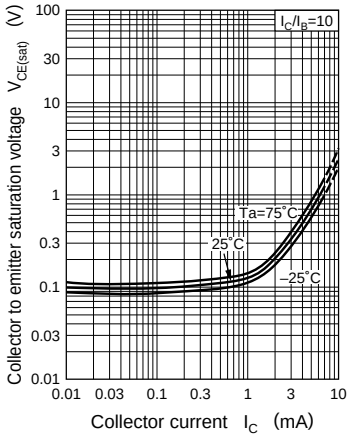
I_C — V_{BE}



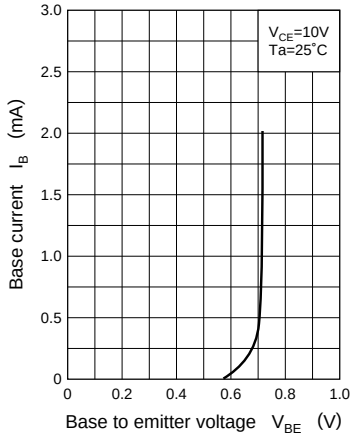
I_C — I_B



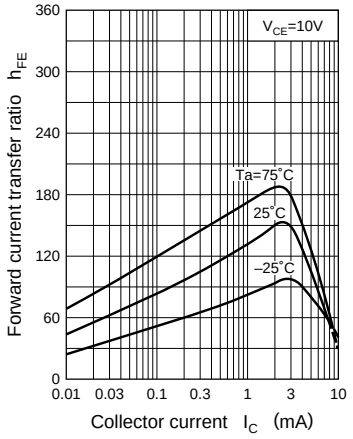
$V_{CE(sat)}$ — I_C



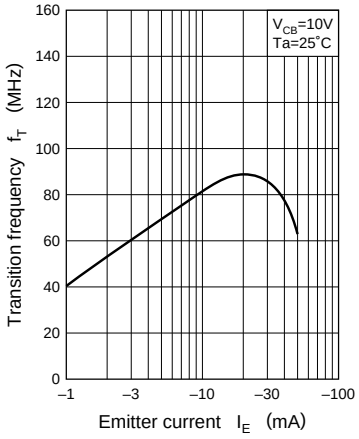
I_B — V_{BE}



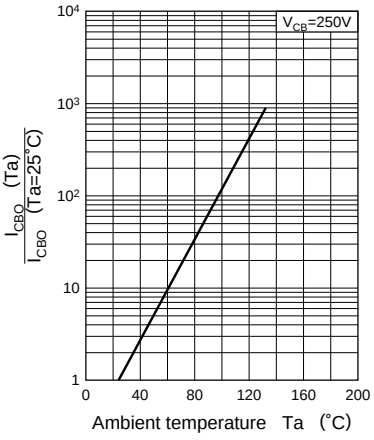
h_{FE} — I_C



f_T — I_E



I_{CBO} — Ta



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